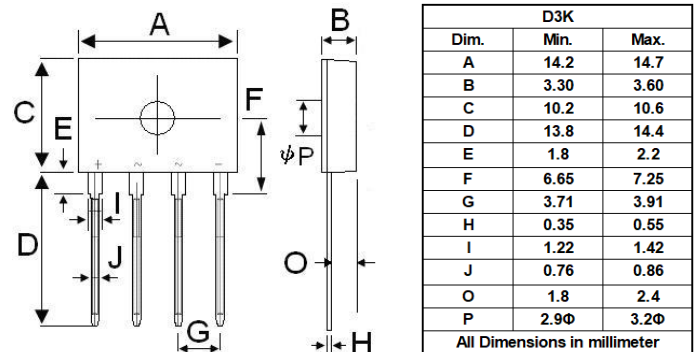


D3K

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
250°C/10 seconds at terminals



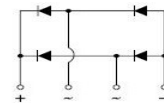
Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	UG4K B05	UG4K B10	UG4K B20	UG4K B40	UG4K B60	UG4K B80	UG4K B100	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current with heatsink	$I_{(AV)}$	4.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	80.0							A
Rating for fusing (t=8.3ms, $T_A=25^{\circ}C$)	I_t^2	26.56							A_s^2
Maximum instantaneous forward voltage at 4.0A	V_F	1.10							V
Maximum DC reverse current $T_A = 25^{\circ}C$ at rated DC blocking voltage $T_A=125^{\circ}C$	I_R	5.0 500							μA
Typical junction capacitance (Note 1)	C_J	38.0							pF
Typical thermal resistance	R_{QJA}	55.0							$^{\circ}C/W$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^{\circ}C$

Note: 1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

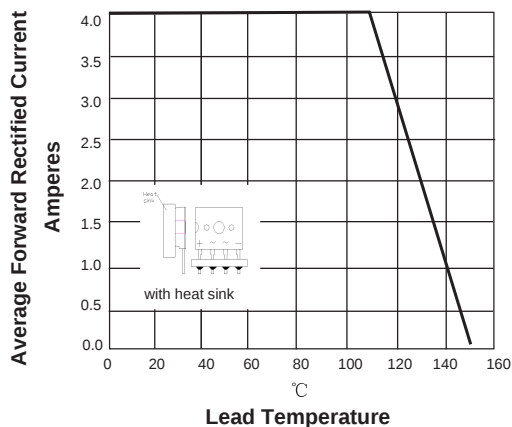


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

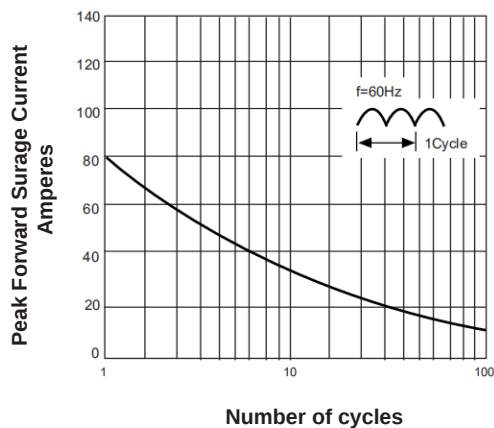


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

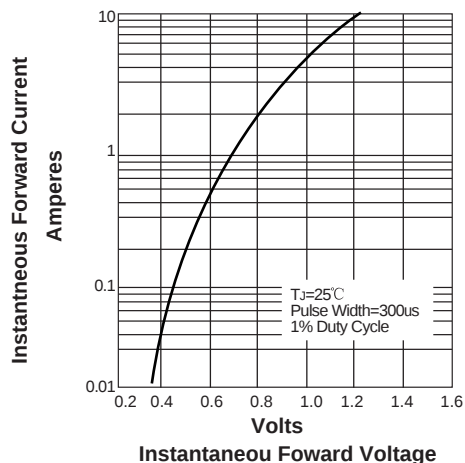
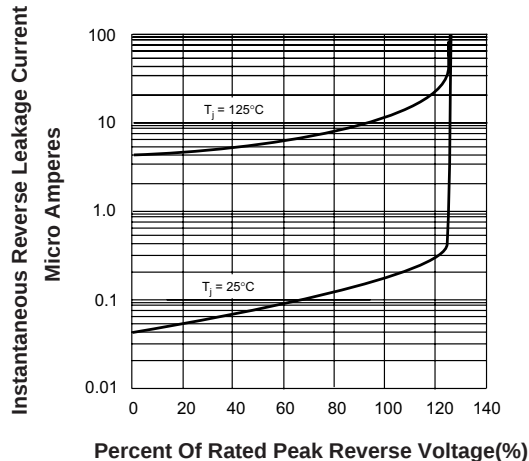
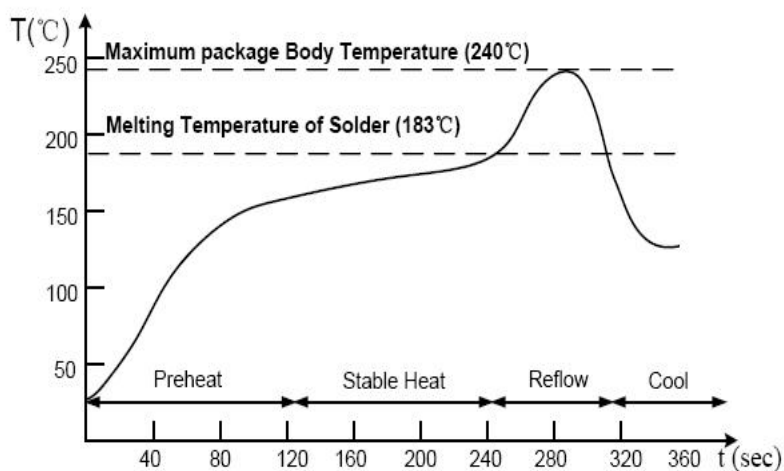


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tube Package

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
D3K	445*30.7*5.6	0.03	495*130*70	1.2	520*370*155	6